Next Generation of Pattern Viafill Plating Technology | 下一代二次铜填盲孔电镀铜技术

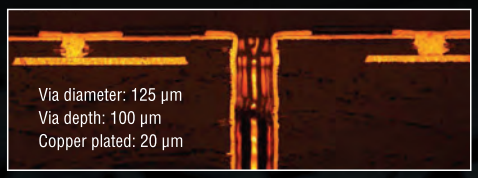
MICROFILL™ EVF Copper Via Fill

The latest generation technology developed by Dow Electronic Materials for advanced viafill plating, MICROFILL™ EVF Via Fill provides enhanced via filling, with simultaneous through-hole plating, at surface thicknesses unattainable. Formulated to operate in existing equipment over a broad range of operating conditions, MICROFILL™ EVF Copper Via Fill is suitable for both HDI and IC Substrate applications. It is proved by sufficient experience that MICROFILL™ EVF could help to reduce 20% plating thickness and helps to improve varied plating defects.

MICROFILL™ EVF, 陶氏电子材料所发展最新一代高阶填盲孔电镀技术， 具备卓越的填孔表现, 并同时兼顾通孔贯孔以及盲孔填孔. 此系统可应用于现有的设备上并具备广泛的操作范围. MICROFILL™ EVF可应用于 HDI 与 IC Substrate 电镀. 藉由相当的经验显示, MICROFILL™ EVF, 得以有效的降低20%的电镀厚度并改善多种电镀缺陷.

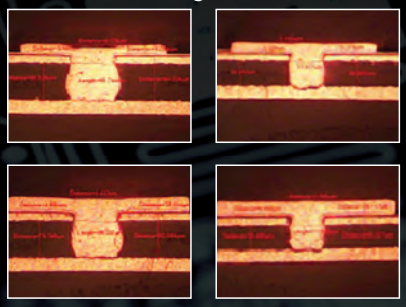
Advantages of MICROFILL™ EVF
MICROFILL EVF 具备以下优越的特性

- Low plating thickness (20 µm)
  较薄的电镀厚度 (20 µm)
- Exceptional microvia filling performances
  优越的盲孔电镀填孔表现
- Simultaneous microvia filling and through-hole plating at HDI application
  于HDI制程中, 可同时兼顾填孔表现及通孔深度贯孔能力
- Rectangle trace profile for W/B application
  线路形状方正, 可搭配使用于打线製程
- Excellent reliability
  优良可靠性
- Easily analyzed and controlled by conventional CVS
  容易控制, 可用CVS测量
- Compatibility with both panel and pattern plating processing
  可适用于全板或二次铜电镀流程

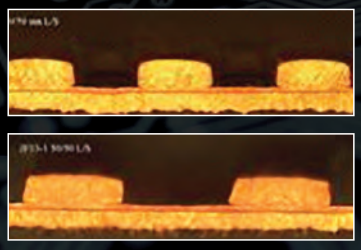


Through hole throwing power >80% (for 5:1 AR through hole at 1.8 ASD and 20 µm copper thickness

Pattern Filling Performance



Trace Profile



50 µm Line / 50 µm Space

Dow Electronic Materials

®™ Trademarks of The Dow Chemical Company ("Dow") or an affiliated company of Dow